

ANTREX Electronics

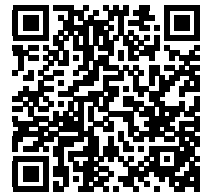
Electronic Components Sourcing Information

Product Reference Information

Part Number: MADP-000235-10720T
Manufacturer: MACOM Technology Solutions
Package: 2-SMD
Availability: Please confirm with sales

Product Page:

<https://antrexco.com/product/details/macom-technology-solutions/madp-000235-10720t.html>



Scan for product page

Request a Quote:

[Submit RFQ for this part](#)

Contact Information

Email: info@antrexco.com

WhatsApp: +86-186-8066-5326

Website: <https://antrexco.com>

Quality & Trust

New & Original Components

Supplier verification and packaging condition review

CoC / RoHS / REACH documents available on request

Secure sourcing support for OEM / EMS projects

Note:

This PDF includes an ANTREX product reference cover page.

The original manufacturer datasheet follows from the next page.

Non-Magnetic MELF PIN Diode

Rev. V1

Features

- Non-Magnetic Package Suitable for MRI Applications
- Rectangular MELF SMQ Ceramic Package
- Hermetically Sealed
- RoHS Compliant* and 260°C Reflow Compatible

Description

The MADP-000235-10720T is a surface mountable PIN diode in a non-magnetic **M**etal **E**lectrode **L**eadless **F**aced (MELF) package. MADP-000235-10720T incorporates M/A-COM's time proven HIPAX technology to produce a low inductance ceramic package with no ribbons or wires. The package utilizes M/A-COM's unique non-magnetic plating process that provides for a hermetically sealed package with extremely low permeability. Incorporated in the package is a passivated PIN diode chip that is full face bonded on both the cathode and anode to maximize the surface contact area for lower electrical and thermal resistance. The chip and package have been comprehensively characterized both electrically and mechanically to ensure repeatable and predictable performance.

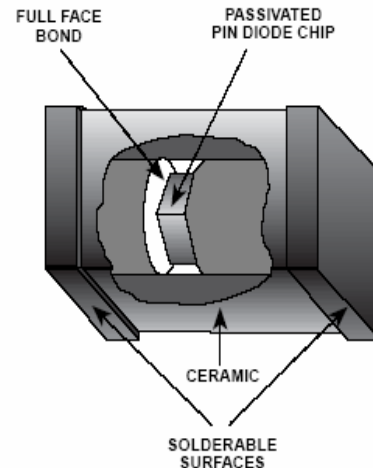
Application

The MADP-000235-10720T is designed for circuit protection and tuning of RF coil designs in MRI applications. When connected in an anti-parallel configuration these PIN diodes provide protection from

Designed for Automated Assembly

This SMQ PIN diode has been designed for high volume tape and reel assembly. The rectangular package design provides for highly efficient automatic pick and place assembly techniques. The parallel flat surfaces are suitable for key jaw or vacuum pickup techniques. All solderable surfaces are tin plated and compatible with most reflow and vapor phase soldering methods.

MELF Internal Construction



Absolute Maximum Ratings^{1,2} @ 25°C

Parameter	Absolute Maximum
Reverse Voltage	-35 V
Forward Current	1.5 A
Operating Temperature	-55°C to +150°C
Storage Temperature	-55°C to +175°C

1. Exceeding these limits may cause permanent damage to the device.
2. Values will re-rate over temperature.

* Restrictions on Hazardous Substances, European Union Directive 2002/95/EC.

Non-Magnetic MELF PIN Diode

Rev. V1

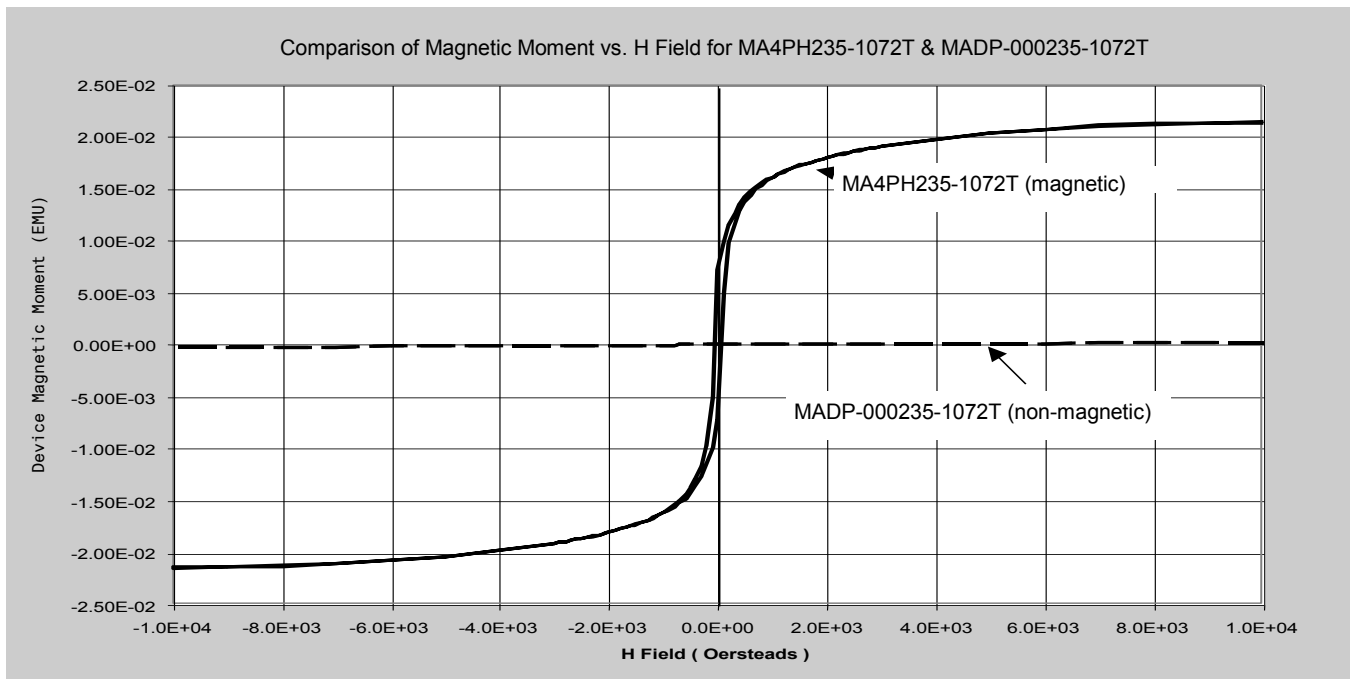
Electrical Specifications @ $T_{AMB} = +25^{\circ}\text{C}$

Part Number	Min. ³ Rev. Volt. $V_R @ 10\mu\text{A}$	Max. ⁴ Capacitance $C_t @ 10\text{V}$	Max. Series Res. $R_s @ 10\text{mA}$ $f = 100\text{MHz}$	Min. Parallel Res. $R_p @ 0\text{V}$ $f = 100\text{MHz}$	Thermal Resistance	Power Dissipation Rating	Nom. Characteristics	
	Volts	pF	Ω	Ω	$^{\circ}\text{C/W}$	Watts	Carrier ⁵ Lifetime μS	I-Region Width Mils
MADP-000235-10720T	35	1.2	0.5	5K	20	7.5	0.3	0.4

Notes:

3. The minimum specified V_R (Reverse Voltage) is sourced and the resultant reverse leakage current, I_r , is measured to be $<10\mu\text{A}$.
 4. Capacitance is specified at 1MHz.
 5. Nominal carrier life time specified with diode biased at $I_F = +10\text{mA}$, $I_{REV} = -6\text{mA}$

Typical Non-Magnetic Performance



Magnetic Property	MADP-000235-1072T	MA4PH235-1072T
Saturation Moment (EMU) @ $H = H_{MAX}$ Oersteds	2.3×10^{-4}	2.1×10^{-2}
Remanance Moment (EMU) @ $H = 0$ Oersteds	4.2×10^{-8}	7.1×10^{-3}
Coercivity (Oersteds) @ EMU = 0 Moment	1	59.2

Non-Magnetic MELF PIN Diode

Rev. V1

Cleanliness and Storage

- ◆ These devices should be handled and stored in a clean environment.
- ◆ Ends of the device are tin plated for greater solderability.
- ◆ Continuous exposure to high humidity (>80%) for extended periods may cause the surface to oxidize. Caution should be taken when storing devices for long periods.

ESD

- ◆ These devices are susceptible to ESD and are rated Class 2, HBM.

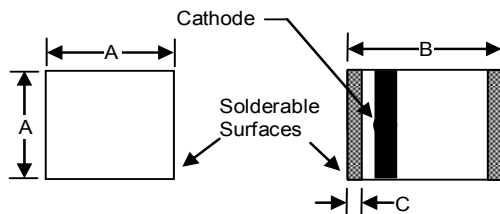
General Handling

- ◆ Device can be handled with tweezers or vacuum pickups and are suitable for use with automatic pick-and-place equipment.

MELF Assembly Recommendations

- ◆ Devices may be soldered using standard 60Sn/40Pb or RoHS compliant solders. MELF devices are tin plated 50 μ M thick to ensure an optimum connection.
- ◆ For recommended Sn/Pb and RoHS soldering profiles See Application Note [M538](#) on the M/A-COM website.

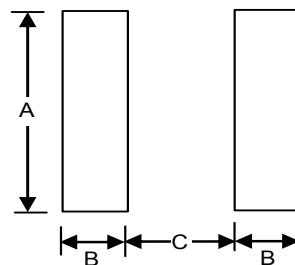
1072 Package Dimensions



Case Style	Size Inches (mm)		
	A (sq) Min./Max.	B Min./Max.	C Min./Max.
1072	0.080/0.095 (2.032/2.413)	0.115/0.135 (2.921/3.429)	0.008/0.030 (.203/.762)

All tolerances are $\pm .001"$ ($\pm .025$ mm).

Circuit Pad Layout



Dimension	Package Style 1072	
	inches	mm
A	0.093	2.36
B	0.050	1.27
C	0.060	1.52

Ordering Information

(Diodes are available in tape and reel in quantities shown below)

Package Style	Quantity 7" Reel
1072T	1500

Tape and reel information can be found on the M/A-COM website at <http://www.macom.com/Application%20Notes/pdf/M513.pdf>

M/A-COM Technology Solutions Inc. All rights reserved.

Information in this document is provided in connection with M/A-COM Technology Solutions Inc ("MACOM") products. These materials are provided by MACOM as a service to its customers and may be used for informational purposes only. Except as provided in MACOM's Terms and Conditions of Sale for such products or in any separate agreement related to this document, MACOM assumes no liability whatsoever. MACOM assumes no responsibility for errors or omissions in these materials. MACOM may make changes to specifications and product descriptions at any time, without notice. MACOM makes no commitment to update the information and shall have no responsibility whatsoever for conflicts or incompatibilities arising from future changes to its specifications and product descriptions. No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document.

THESE MATERIALS ARE PROVIDED "AS IS" WITHOUT WARRANTY OF ANY KIND, EITHER EXPRESS OR IMPLIED, RELATING TO SALE AND/OR USE OF MACOM PRODUCTS INCLUDING LIABILITY OR WARRANTIES RELATING TO FITNESS FOR A PARTICULAR PURPOSE, CONSEQUENTIAL OR INCIDENTAL DAMAGES, MERCHANTABILITY, OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT. MACOM FURTHER DOES NOT WARRANT THE ACCURACY OR COMPLETENESS OF THE INFORMATION, TEXT, GRAPHICS OR OTHER ITEMS CONTAINED WITHIN THESE MATERIALS. MACOM SHALL NOT BE LIABLE FOR ANY SPECIAL, INDIRECT, INCIDENTAL, OR CONSEQUENTIAL DAMAGES, INCLUDING WITHOUT LIMITATION, LOST REVENUES OR LOST PROFITS, WHICH MAY RESULT FROM THE USE OF THESE MATERIALS.

MACOM products are not intended for use in medical, lifesaving or life sustaining applications. MACOM customers using or selling MACOM products for use in such applications do so at their own risk and agree to fully indemnify MACOM for any damages resulting from such improper use or sale.